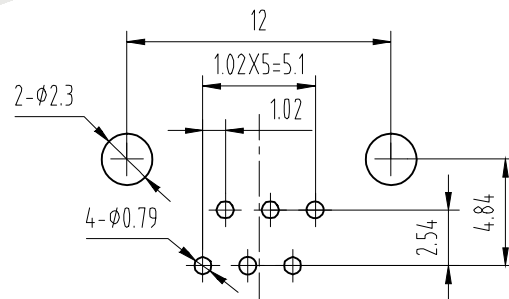
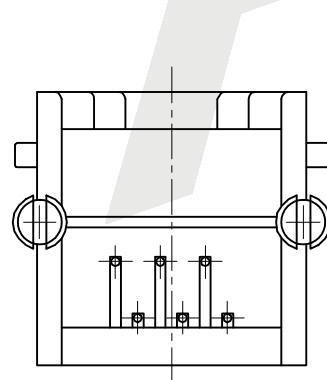
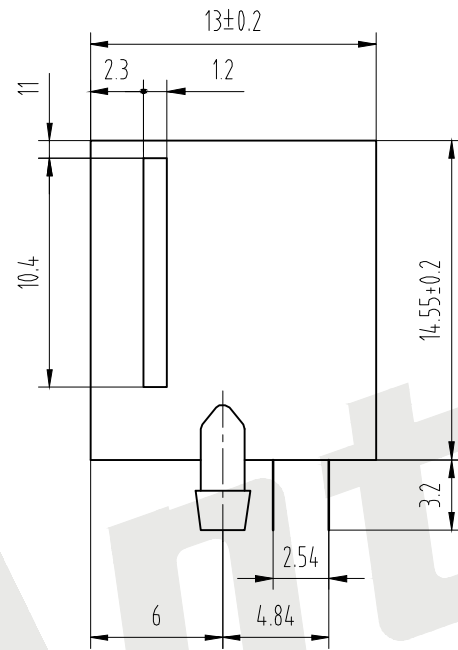
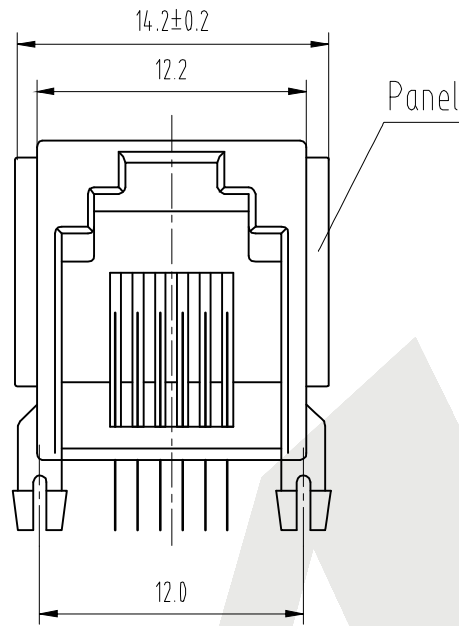


HSF



ROHS



PC Board Layout  
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.30\text{mm}$ .
3. PLATING: SELECTING GOLD PLATING  $3\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATING OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.20mm THICKNESS COPPER ALLY WITH NICKEL PLATE

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5AMP.
3. CONTACT RESISTANCE: 30 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 500 MEGOHMS MIN @500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE

MECHANICAL: 1000V AC RMS 50Hz. 1MIN.

1. DURRABILITY: 750 CYCLES MIN.
2. PCB RETENTION PRE-SOLDER : 1 LB MIN.

ENVIRONMENTAL:

1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$ .
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$ .

Order code:

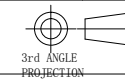
ATRJ5521 - 6P - 6C - X - A - A

- ①      ②      ③      ④      ⑤      ⑥

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating  
G0: Gold flash  
G1: 3U" Gold  
G2: 5U" Gold  
G3: 10U" Gold  
G4: 15U" Gold  
G5: 30U" Gold  
SN: Tin
- ⑤ Shield  
A: W/O Shield  
B: Half Shield  
C: Shield W/Eml  
D: Shield W/O Eml
- ⑥ With Panel or not  
A: With panel  
B: Without panel

Unless Otherwise specified tolerance  
X.  $\pm 0.35$  X.XX:  $\pm 0.20$   
X.X:  $\pm 0.25$  X.XXX:  $\pm 0.15$

SCALE: As Shown	UNIT: mm
DRAW Wu Sai	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018



**Antenk**® ANTENK ELECTRONICS CO., LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

TITLE:  
RJ11 Jack Side entry, Full Plastic, with panel

DRAWING NO: ATRJ5521-6P6C-X-A-A

PRODUCT NO: ATRJ5521-6P6C-X-A-A

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		